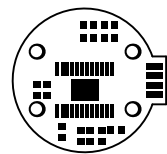
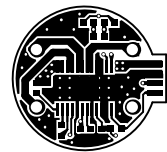


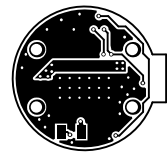
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV10983REF	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/5/2015	4:19:09 PM	TEXAS INSTRUMENTS



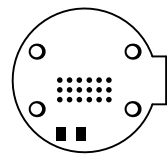
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/5/2015 4:19:10 PM	TEXAS INSTRUMENTS	



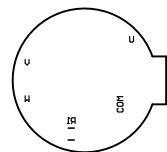
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LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/5/2015 4:19:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV10983REF	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/5/2015 4:19:11 PM	TEXAS INSTRUMENTS	



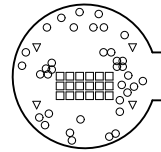
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV10983REF	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/5/2015 4:19:12 PM	TEXAS INSTRUMENTS	



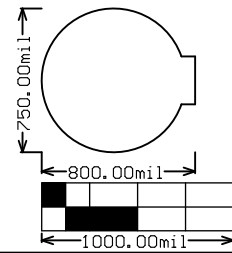
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV10983REF	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/5/2015 4:19:13 PM	TEXAS INSTRUMENTS	

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	18	12.992mil (0.33mm)	PTH	Round
○	36	15mil (0.381mm)	PTH	Round
▽	4	60mil (1.524mm)	PTH	Round
	58 Total			

Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV10983REF	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/5/2015	4:19:13 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV10983REF	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/5/2015	4:19:14 PM	TEXAS INSTRUMENTS

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